



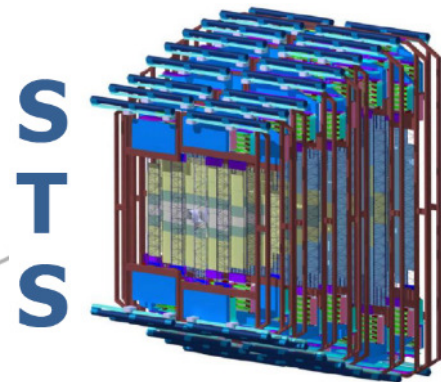
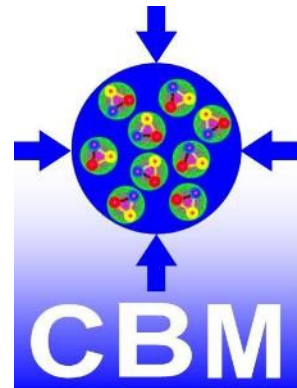
Microstrip and Gas Electron Multiplier Readout ASIC for Physics Experiment at FAIR

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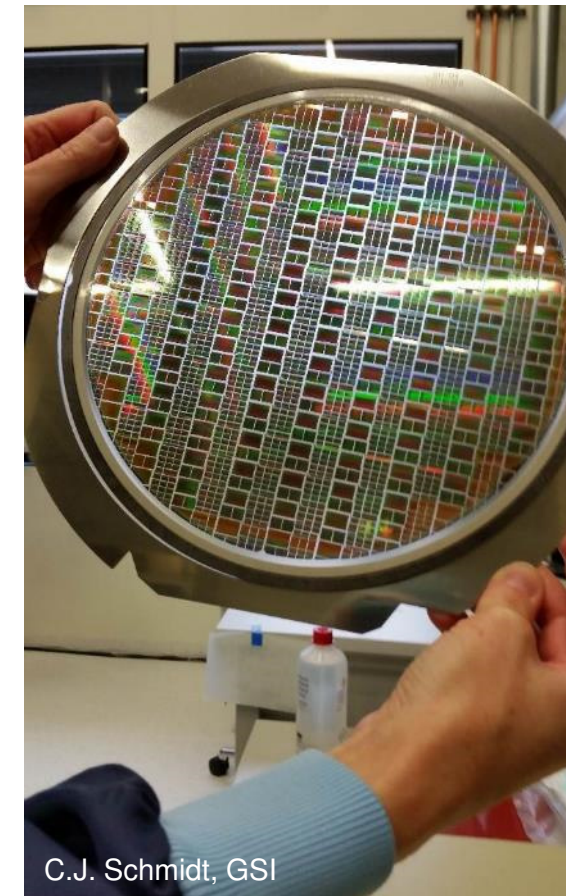
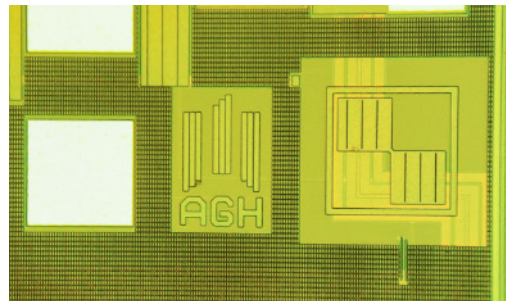
Krzysztof KASINSKI,
Weronika ZUBRZYCKA,
Robert SZCZYGIĘŁ

2017 IWORID, Kraków, Poland



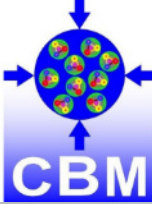
Outline

- Introduction – CBM Experiment, STS & MUCH detectors
- STS/MUCH-XYTER2 ASIC
 - Front-End, Data flow, Protocol & Interface
 - Test system
- Measurement results
- Summary



C.J. Schmidt, GSI

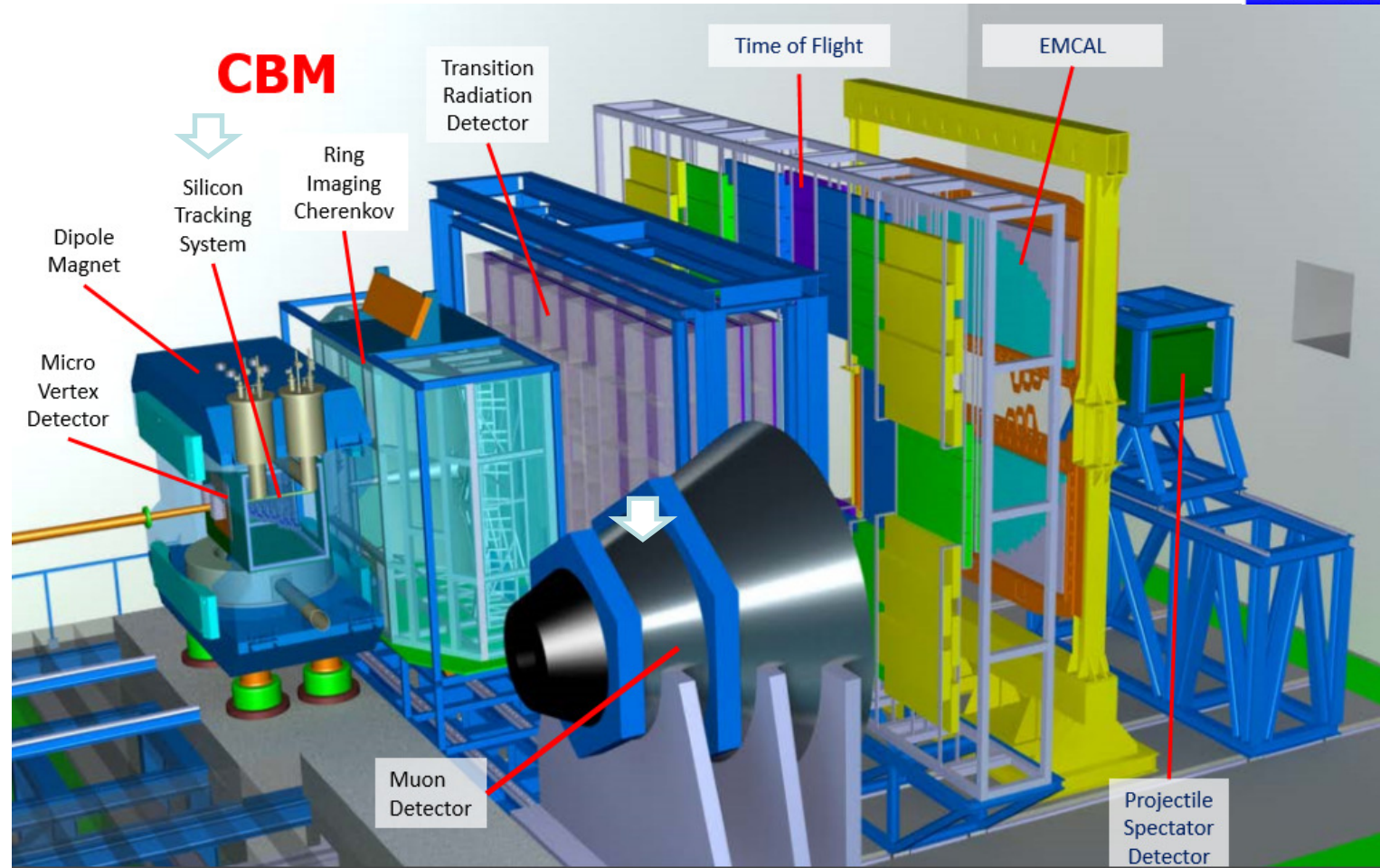
Compressed Baryonic Matter Experiment



Goal: exploration of the QCD phase diagram in the region of very high baryon densities

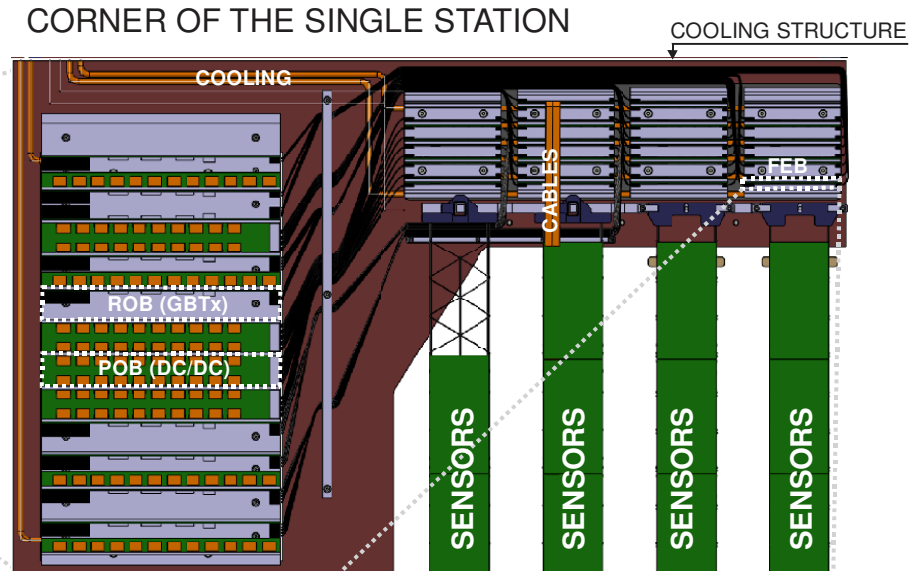
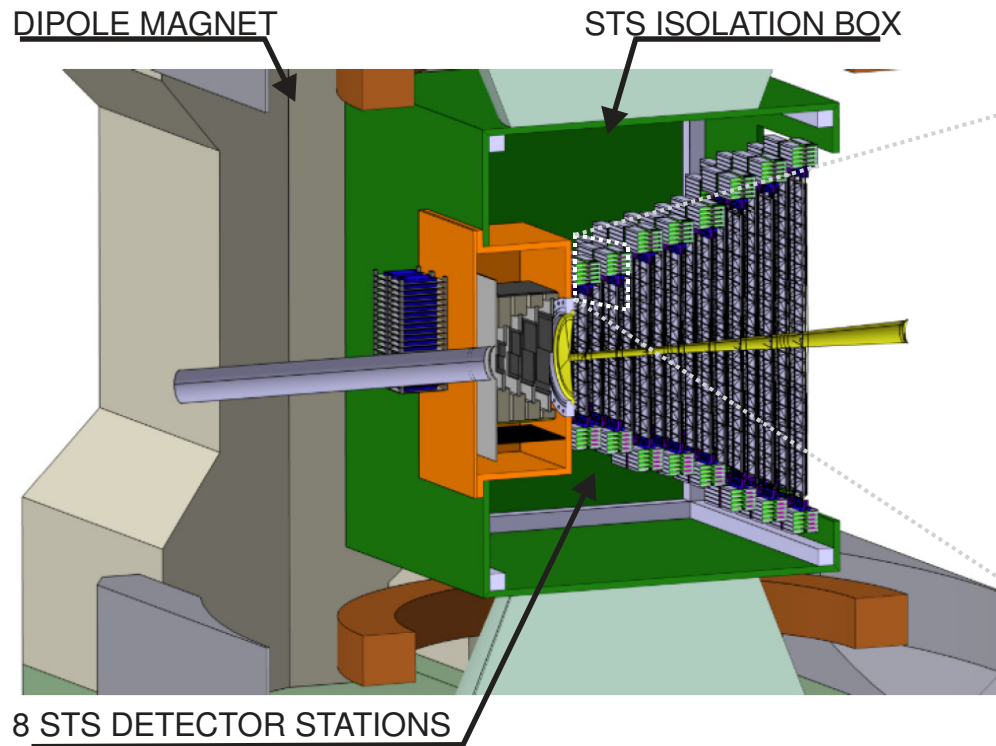
- up to 10 MHz interactions
- **self-triggering** front-end chip
- radiation doses

STS: track reconstruction and momentum determination of charged particles in 1T field, 8 detector stations (30cm – 100 cm from target)



FAIR Facility for Antiproton and Ion Research

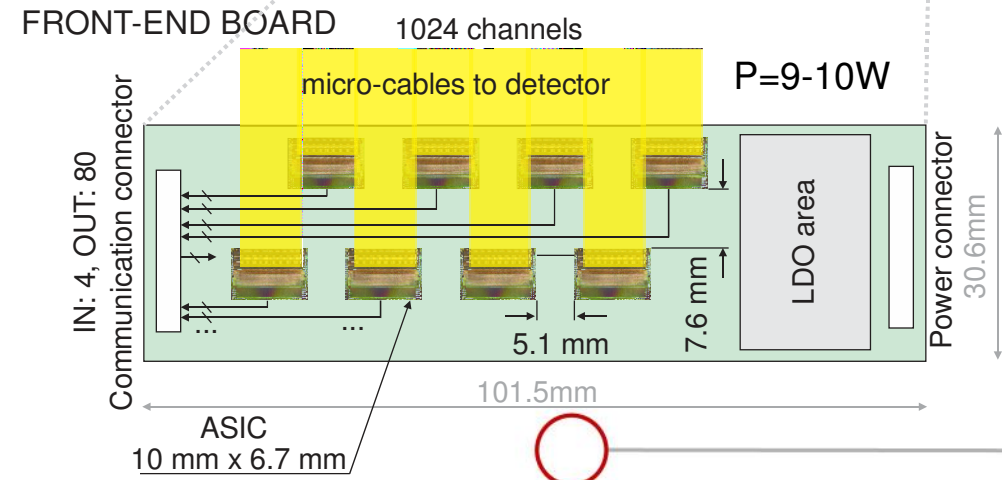
STS system - overview



readout electronics located at the perimeter of the detector stations on FEB boards (8 chips/board).

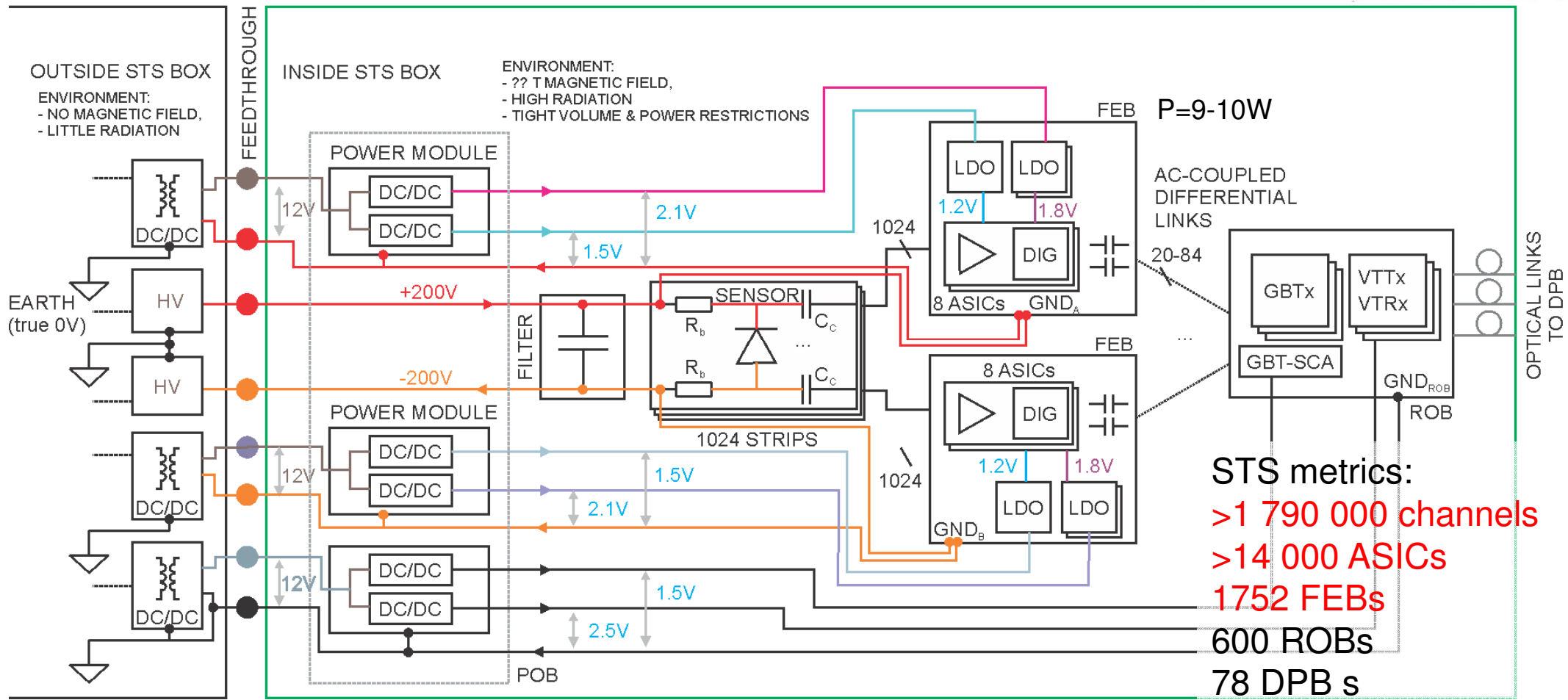
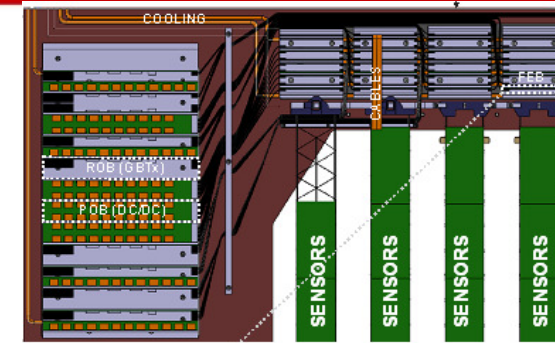
double-sided, micro-strip, 1024 channels per side, 7.5° stereo angle, **58 μm pitch**, lengths 20 - 120 mm, 300 μm thickness,

mock-up demonstrator



STS Power & Readout

LOW-VOLTAGE and HIGH-VOLTAGE POWERING SCHEME (SINGLE SENSOR)



J. Lehnert ; W. F. J. Müller ; C. J. Schmidt;

The GBT-based readout concept for the silicon tracking system of the CBM experiment. [Proc. SPIE 9662, 96622S.](https://doi.org/10.1117/1.5000000)

K. Kasinski, P. Koczon, S. Ayet, S. Loechner, C. J. Schmidt;

System-level Considerations of the Front-End Readout ASIC in the CBM Experiment from the Power Supply Perspective. [Journal of Instrumentation 2017.](https://doi.org/10.1088/1748-0221/18/01/P01001)



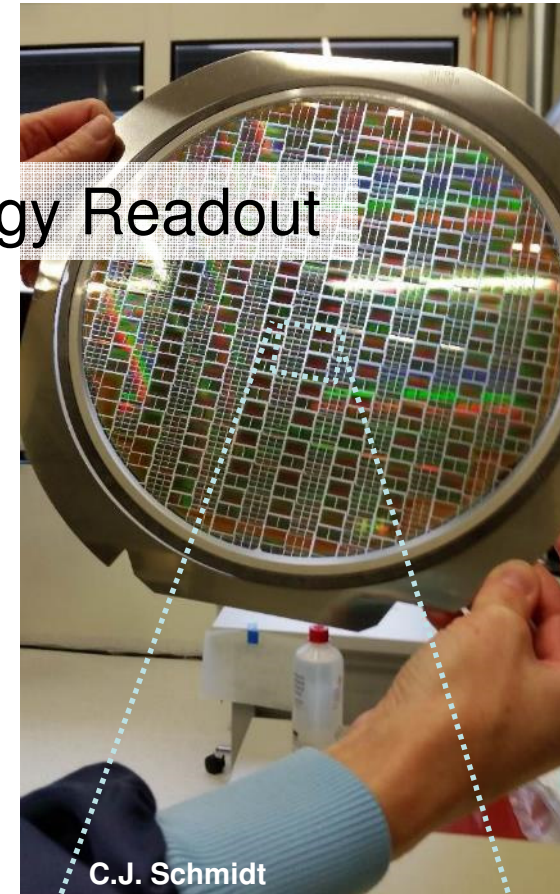
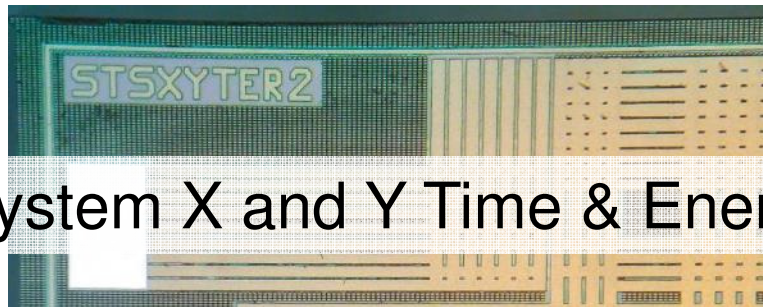
STS-XYTER2

Silicon Tracking System X and Y Time & Energy Readout

UMC 180 nm CMOS Engineering Run 2016 shared between other CBM chips
 Thinning & stealth laser dicing
 10 mm x 6.8 mm die size, 288 pads
 128 channels + 2 diagnostic channels, Power: 1.1 – 1.3 W/chip
 4420 bits of AFE configuration
 54400 gates (after triplication), 12600 flops

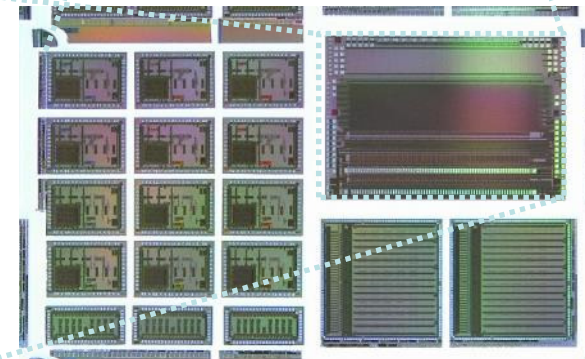
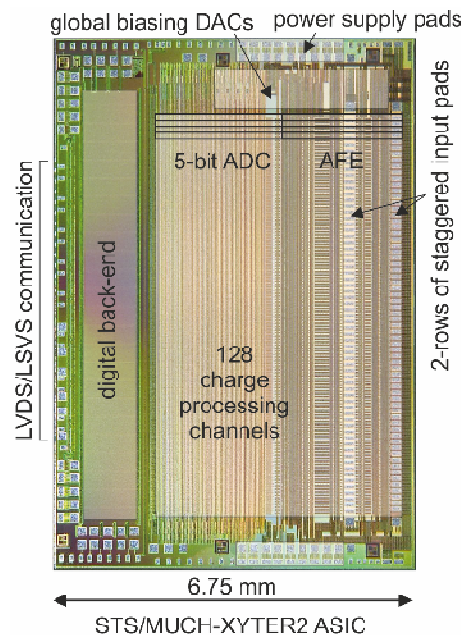
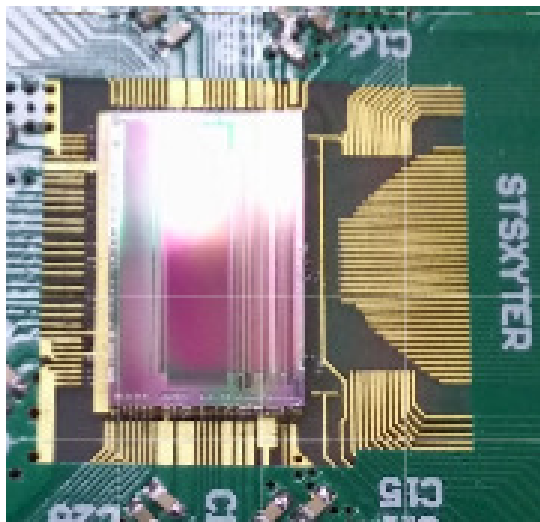
Evolution of the STS-XYTER prototype

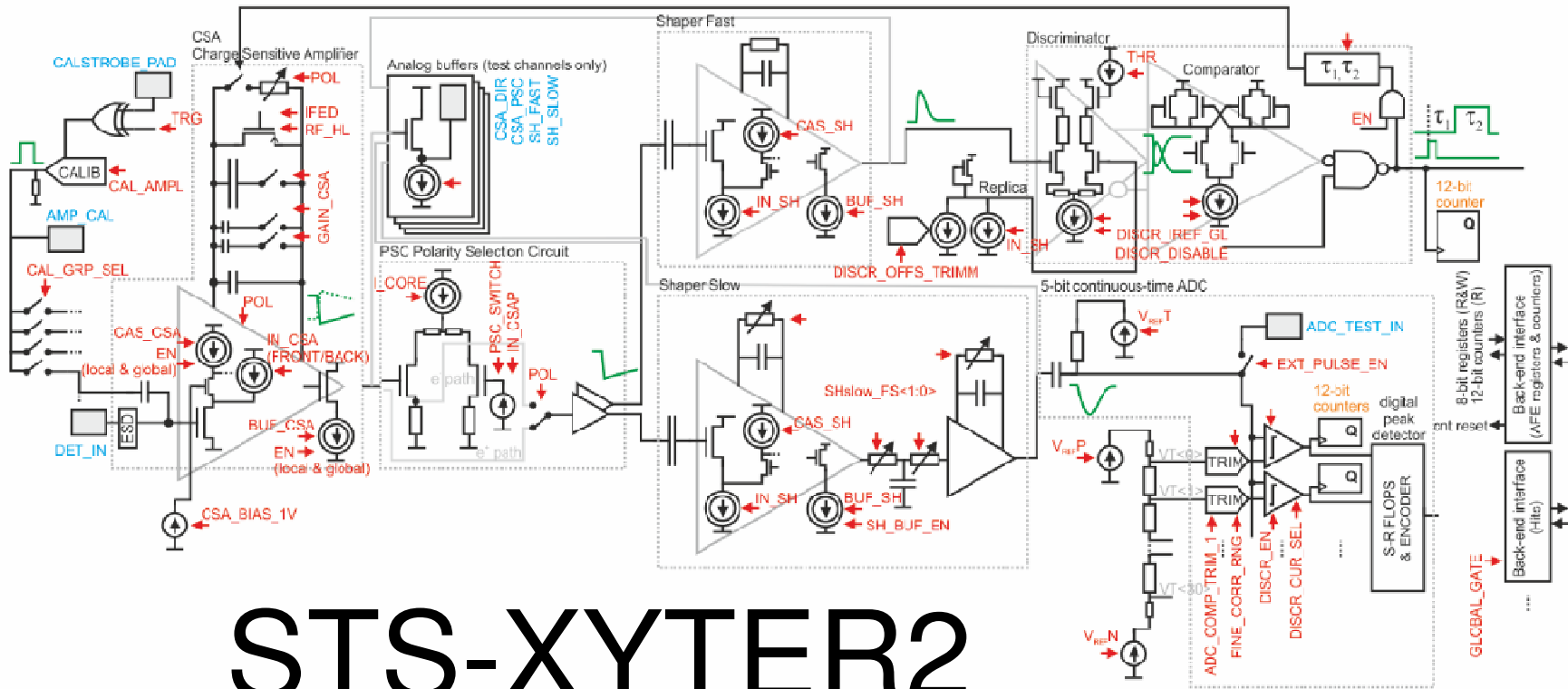
- New CSA & reset circuits
- Enhanced layout & schematics
- New back-end
- Dedicated protocol



C.J. Schmidt

Engineering run wafer after dicing





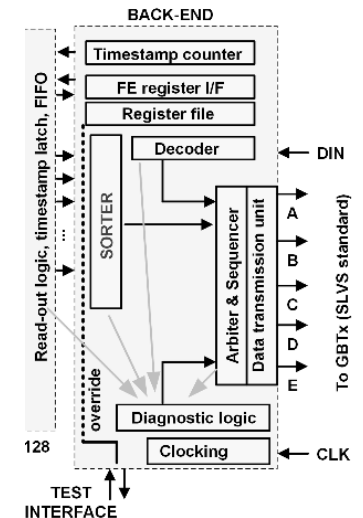
STS-XYTER2

128 channels
time (3.125 ns) & amplitude digitization (5-bit)

0-12 fC electrons & holes (STS)
gain switching & trimming
250 khit/s rate (pulsed reset)
80-280 ns shaping time (slow path)
time-walk corrected offline
continuous-time ADC + peak det.
P=8.5-10 mW/channel (incl. logic)

Back-end:

- control via synthesized reg & AFE DICE cells
- 9.41 – 47 Mhit/s/ASIC data BW
- throttling, diagnostic features
- link loopback (multi-level)
- 64-bit e-fuse for traceability



AFE Channel Layout

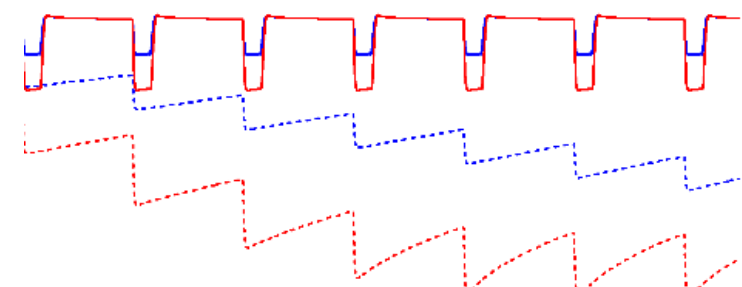
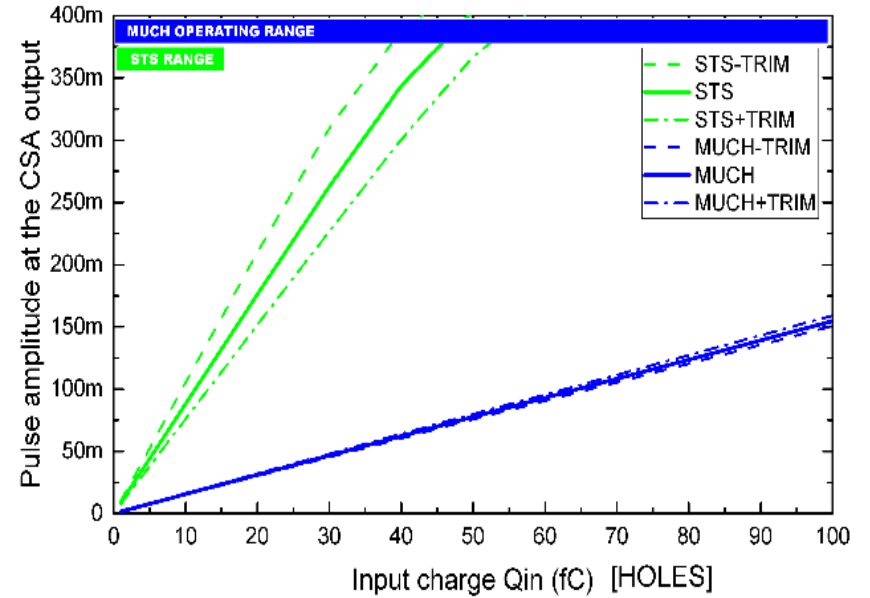
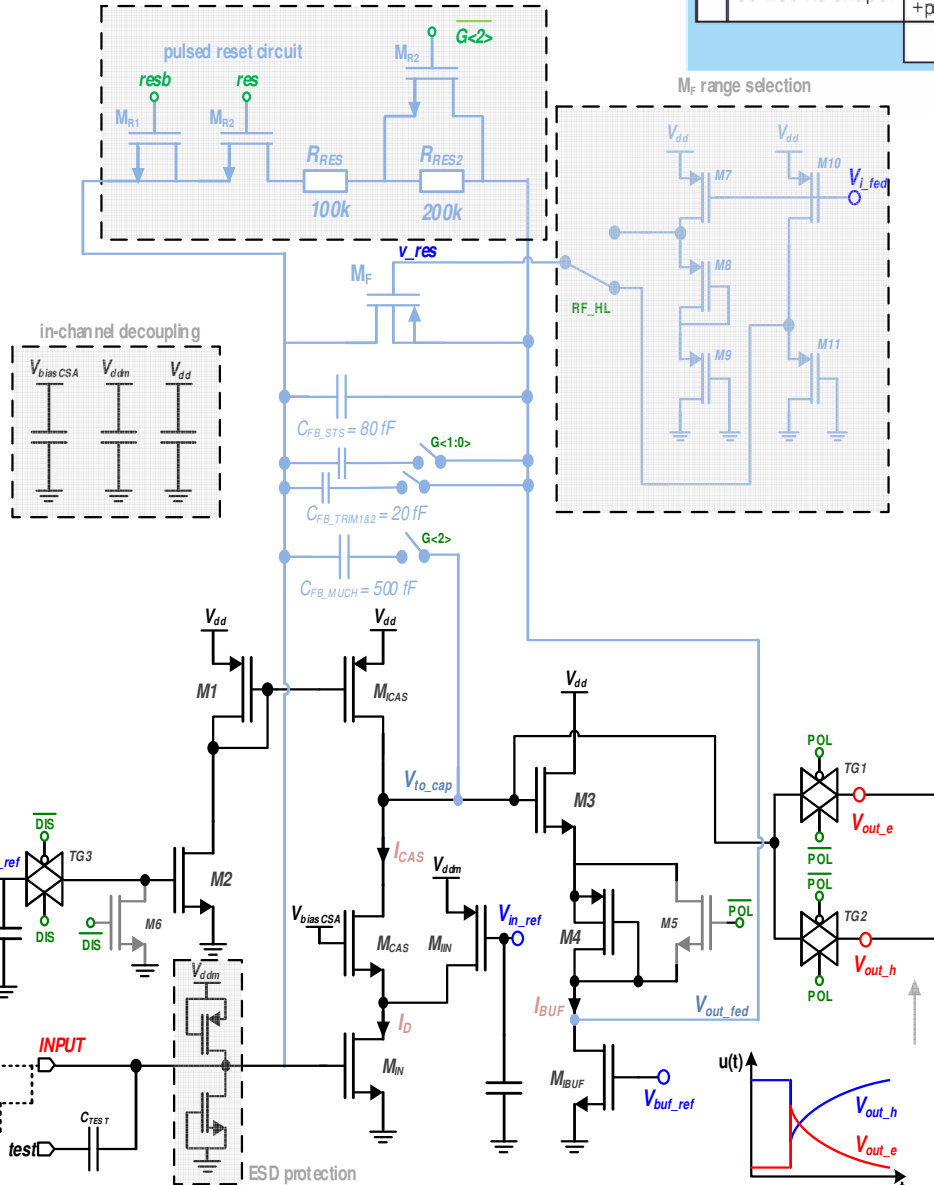
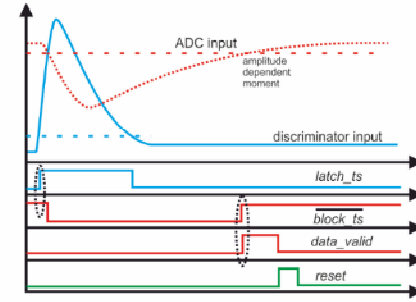
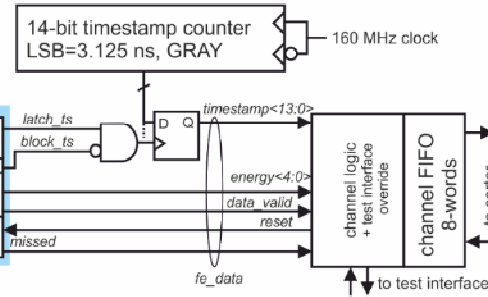


CSA PSC SHfast SHslow Comparator ADC

Short blink on AFE

AFE channel

CSA	30 ns shaper	discriminator
	80-280 ns shaper	ADC 5-bit CT + peak det.
		logic



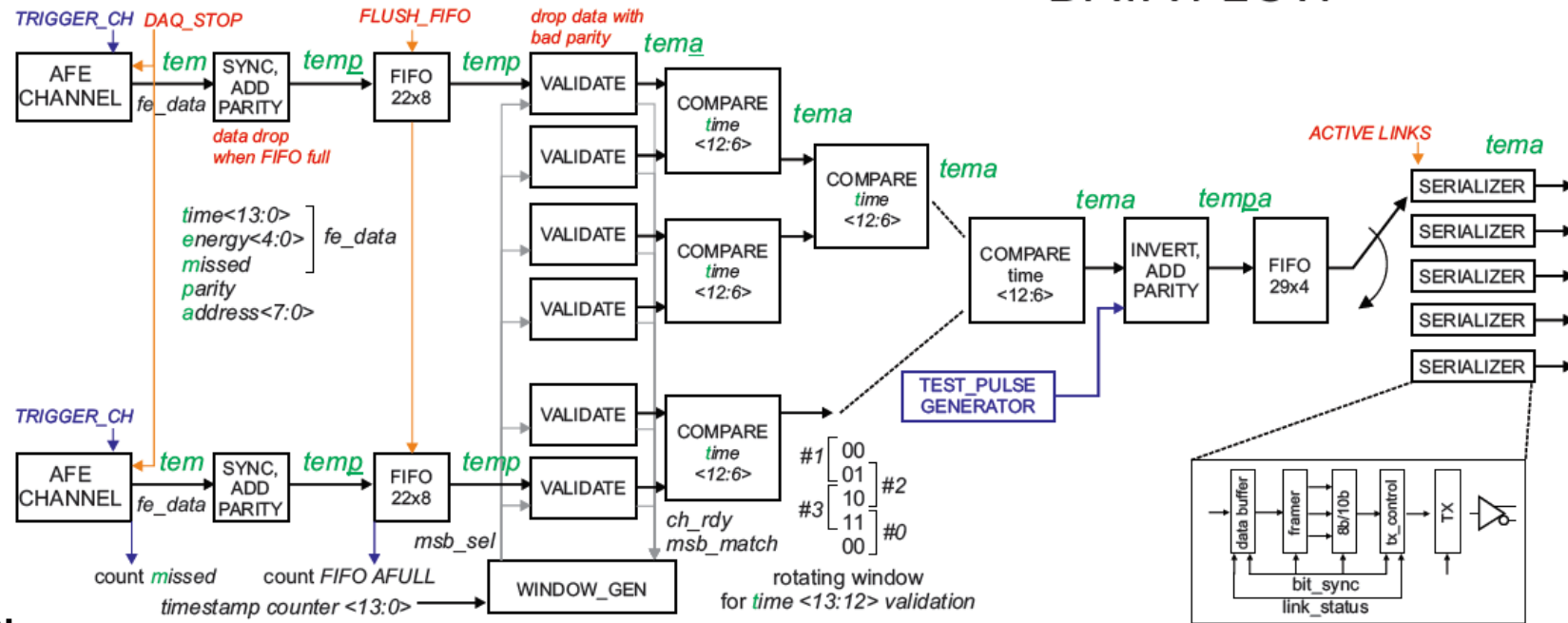
W. Zubrzycka, K. Kasinski
Fast reset of the (...) readout chain in the presence of leakage current
Monday, Poster Session

Temp: -20 – 80 °C $P_{CSA} = 2.7 - 5.1$ mW

Data flow



AFE > Channel FIFO > Sorter > 5 output serializers DATA FLOW

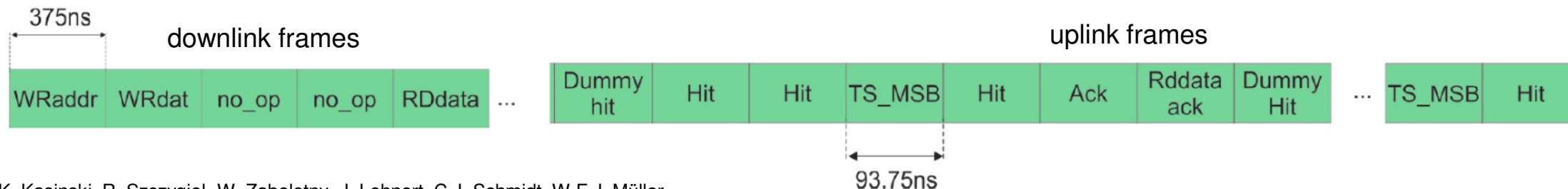


Diagnostic / throttling features:

- test hit generator (multi level, separate generator (rate & content control), channel triggering)
- counting of: event missed, channel FIFO almost full
- channel masking & data drop & FIFOs

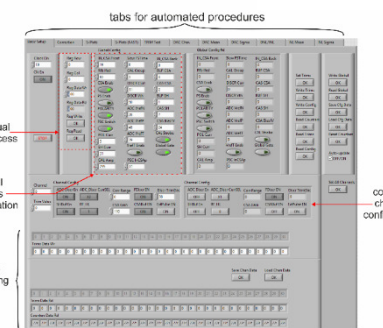
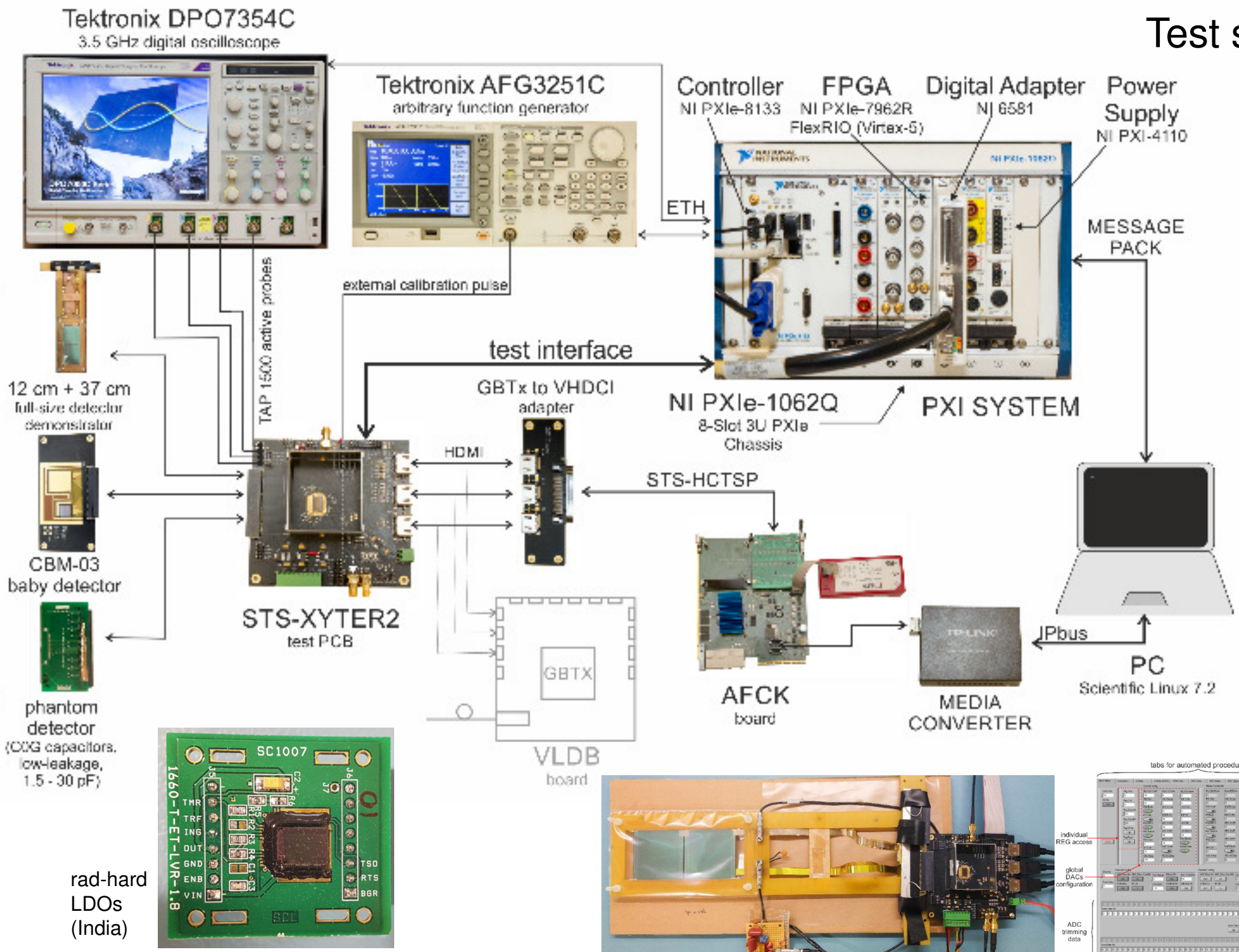
Physical interface on FEB

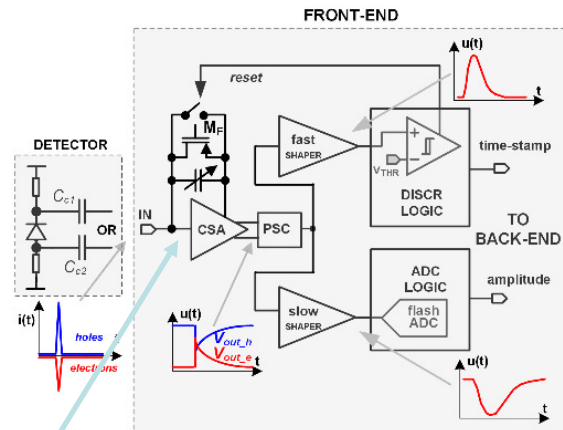
- shared, multi-drop, AC-coupled 160 Mbps clock & data lines (downlink)
- individual, AC-coupled, 320 Mbps (uplink)
- STS-HCTSP Protocol: fully synchronous, 8b/10b encoding, optimized for STS application, novel link synchronization technique, lossless data compression



Test setup

detector modules

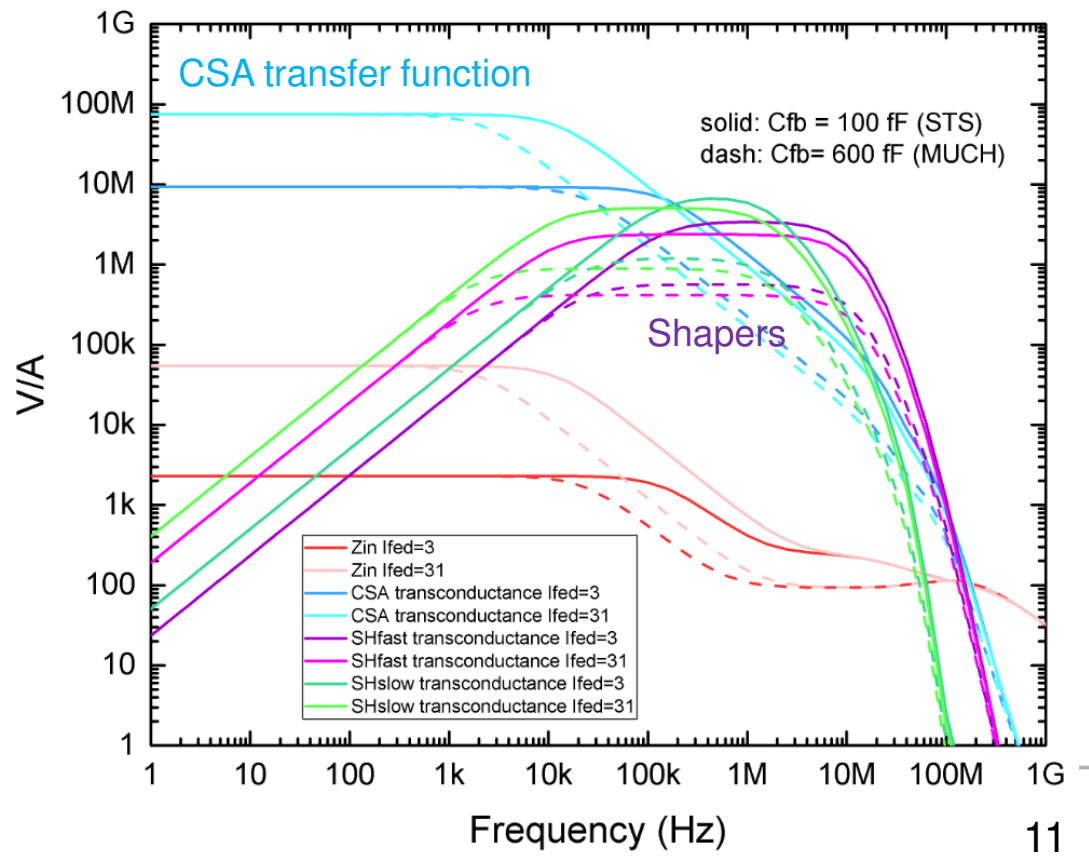
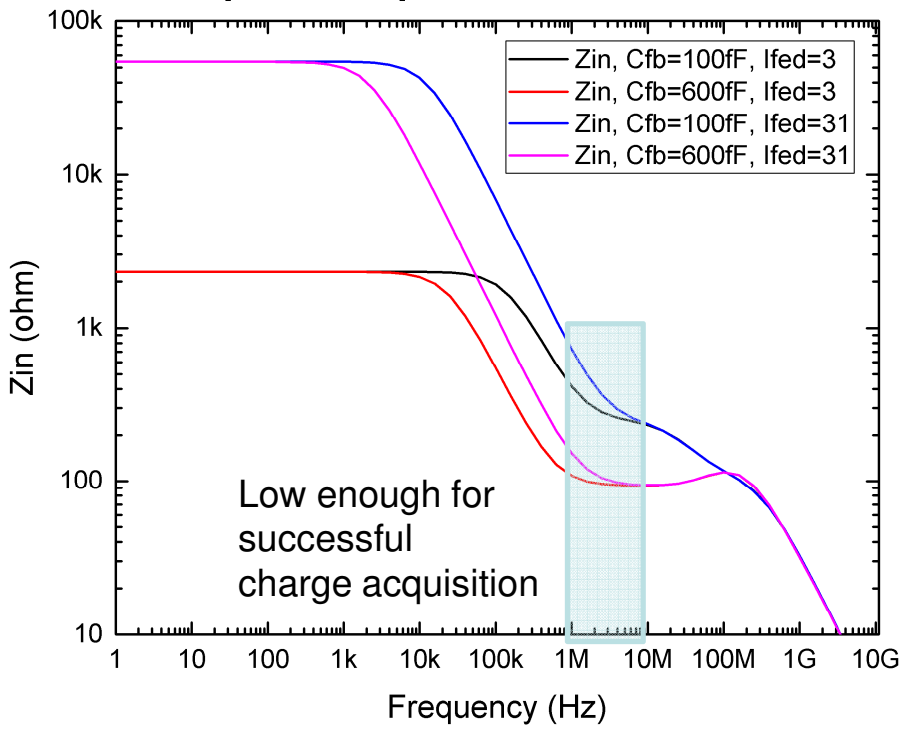




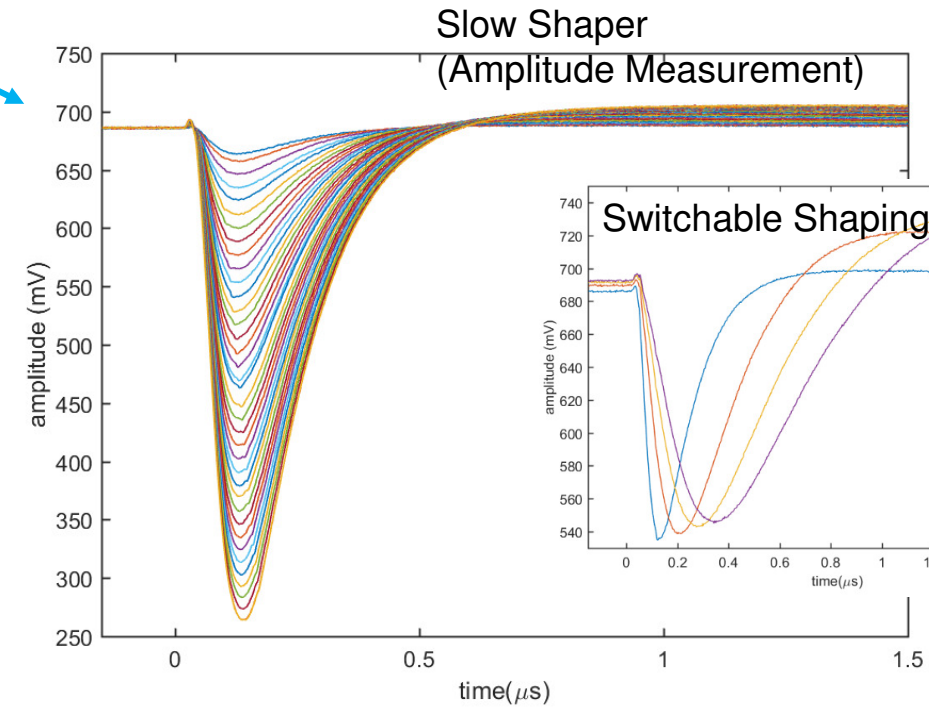
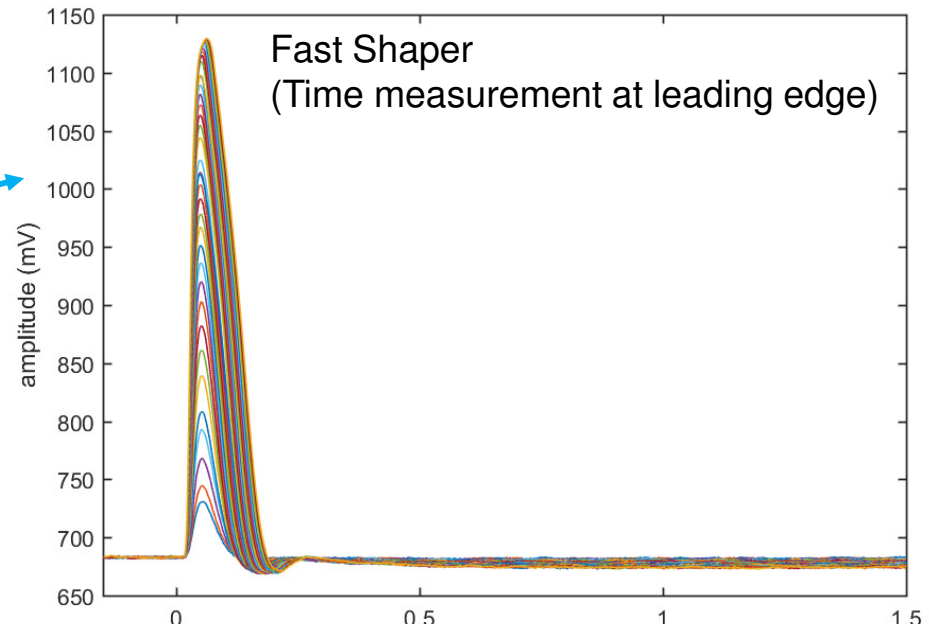
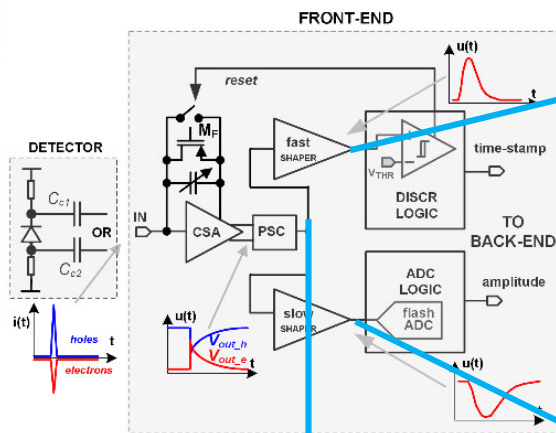
Test results:

- Smoke test: O.K.
- STS-HCTSP Protocol: O.K.
- HW chip addressing: O.K.
- synthesized registers access: O.K.
- DICE AFE registers access: O.K.
- Test hit generator: O.K.
- TS_MSB frame generation O.K.

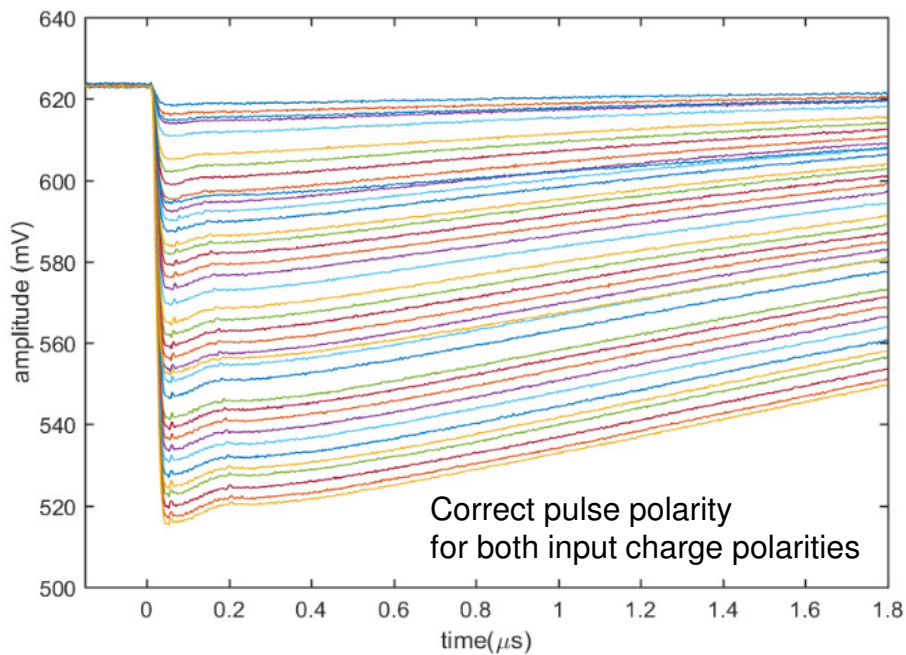
Input impedance



Measured waveforms

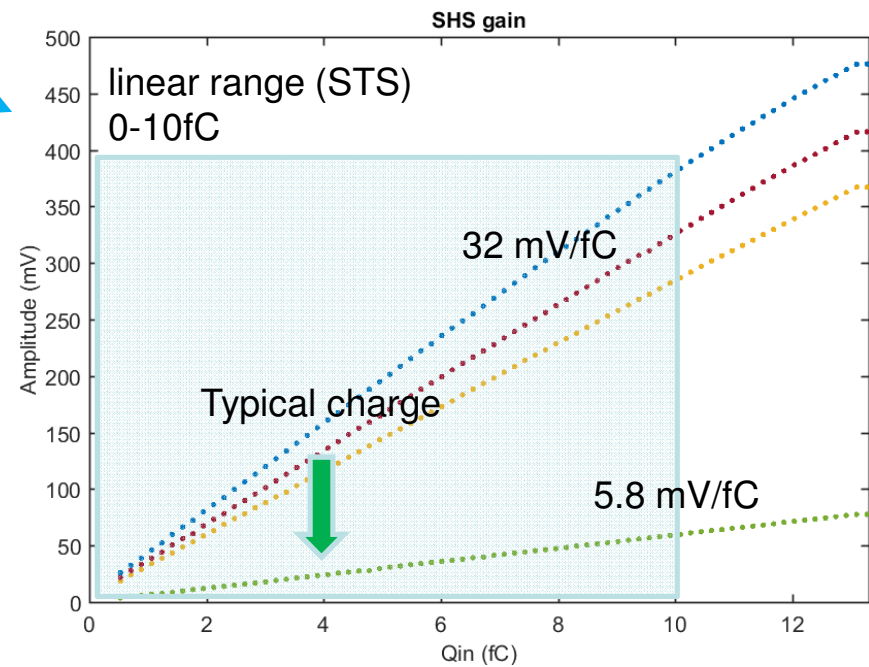
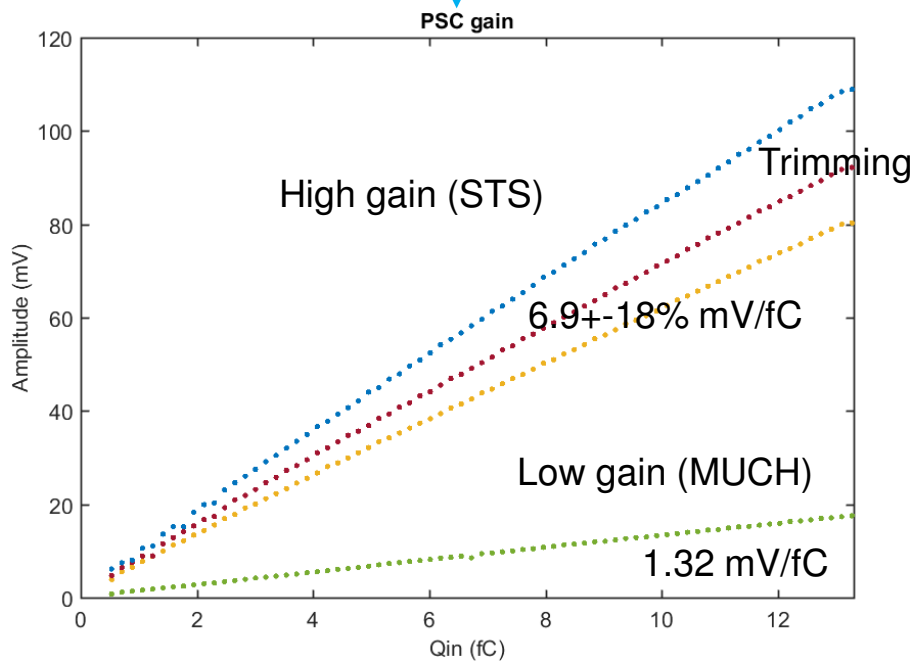
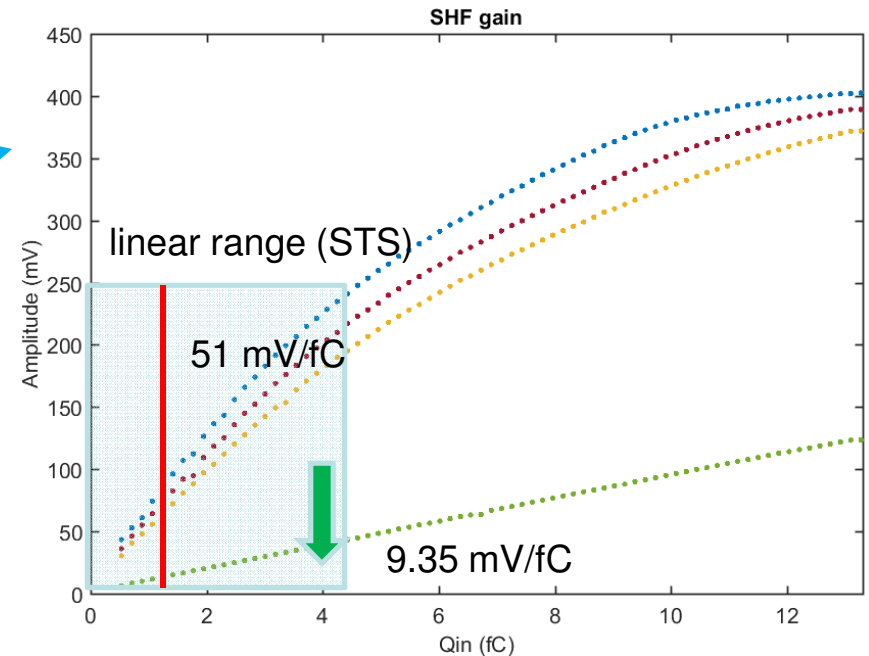
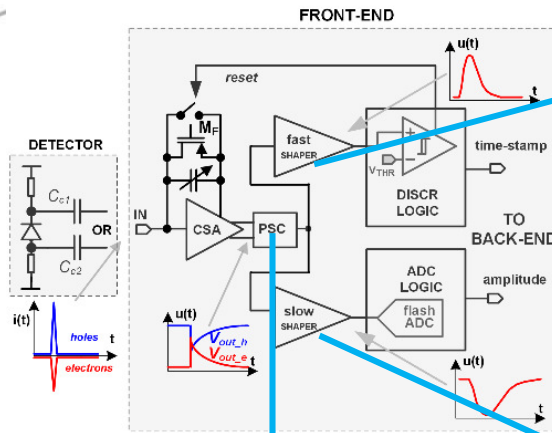


Polarity Selection Circuit



Shaping time setting	0	1	2	3
Measured t_p (ns)	116	190	262	332
Simulated t_p (ns)	90	150	220	280

Measured gain characteristics

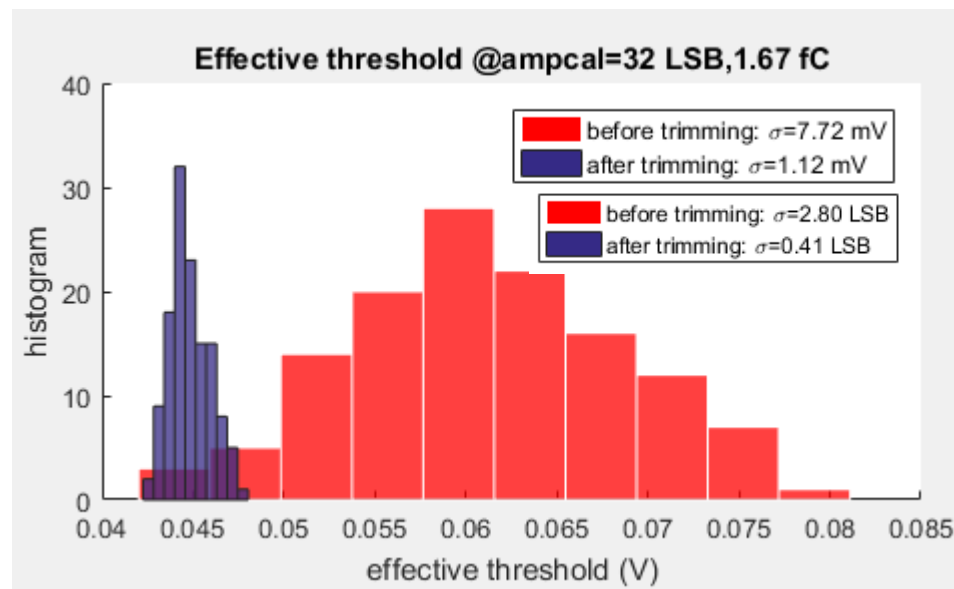
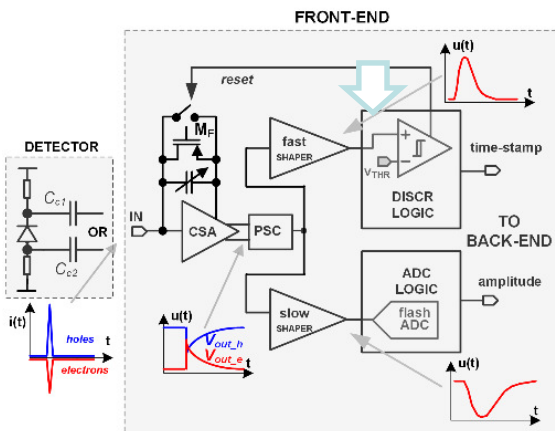
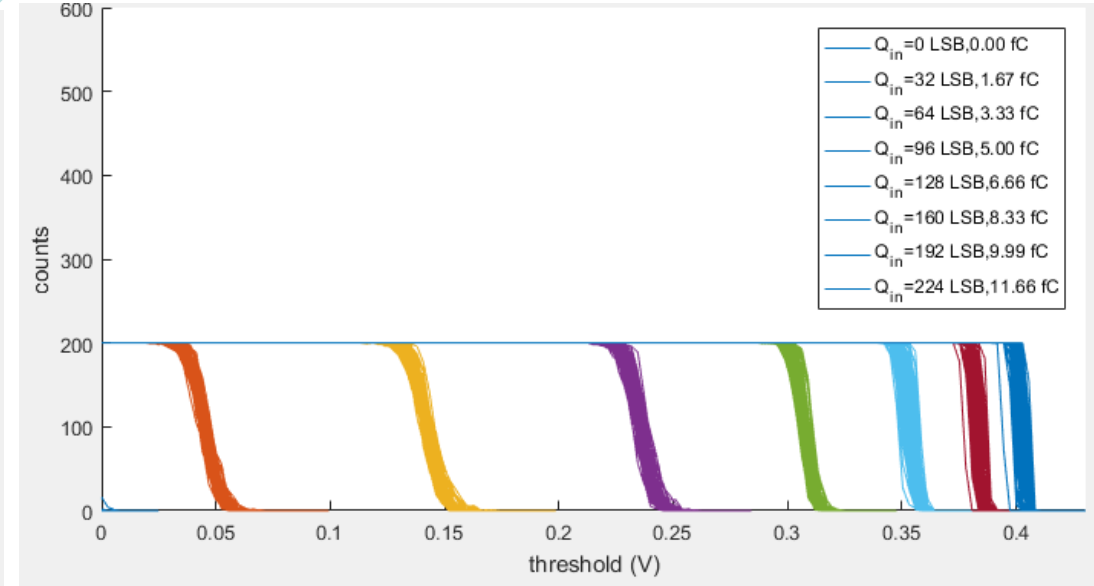
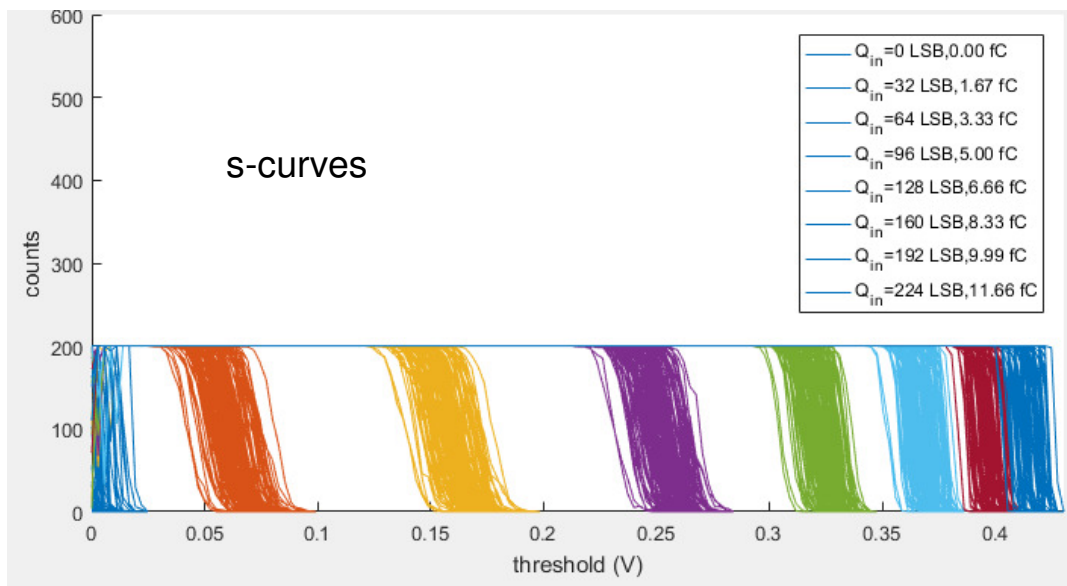


Measured effective discriminator offset spread (128 channels)

Before trimming

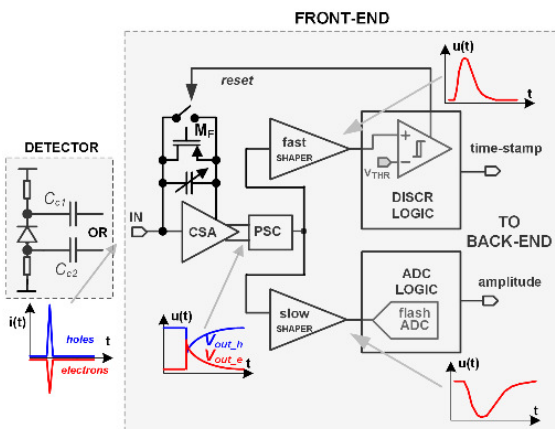
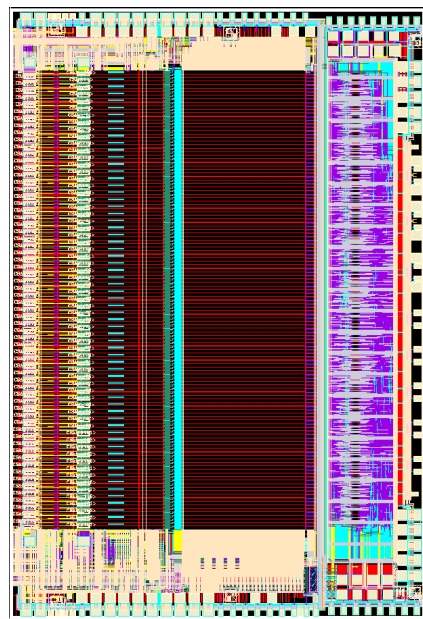


After trimming



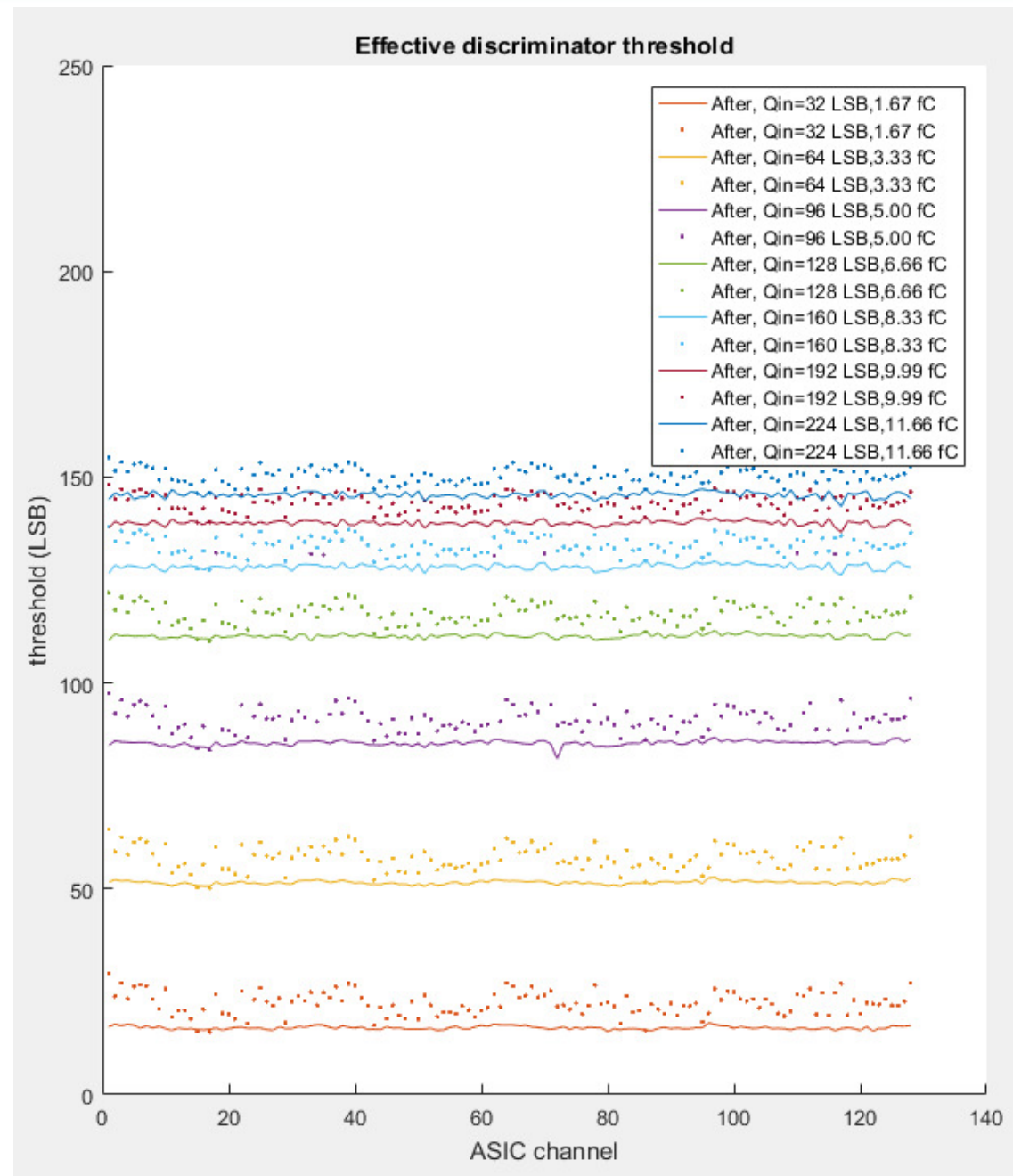
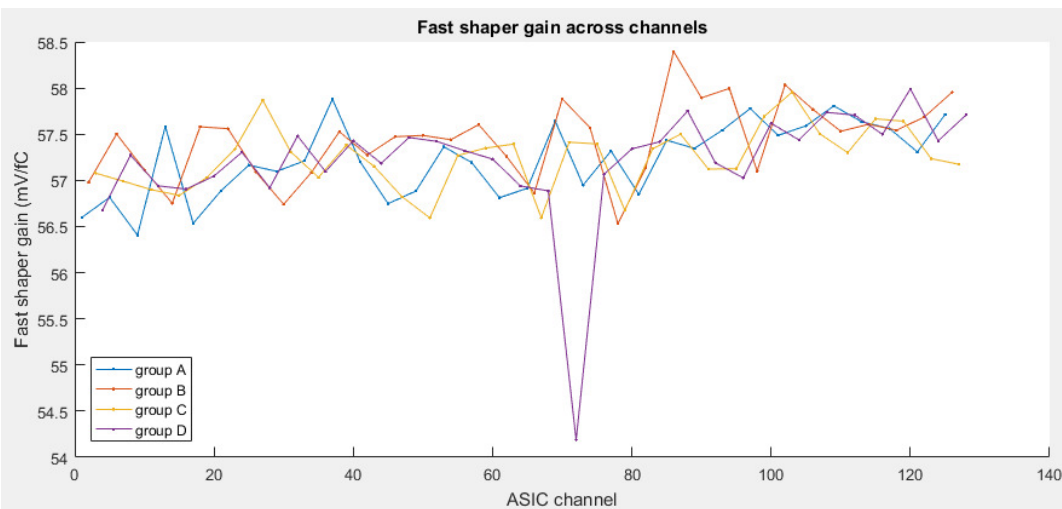
Good matching with simulations.

Low offset spread after trimming.



No visible trends across the channels:

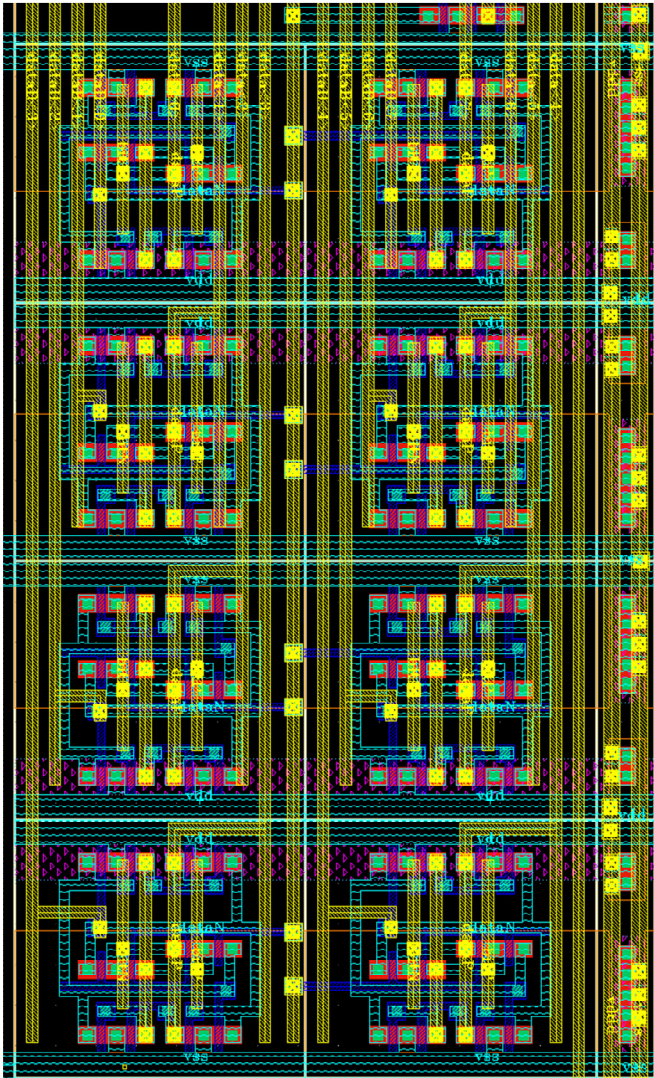
- No problematic DC voltage drop on power lines
- No visible problems with biasing





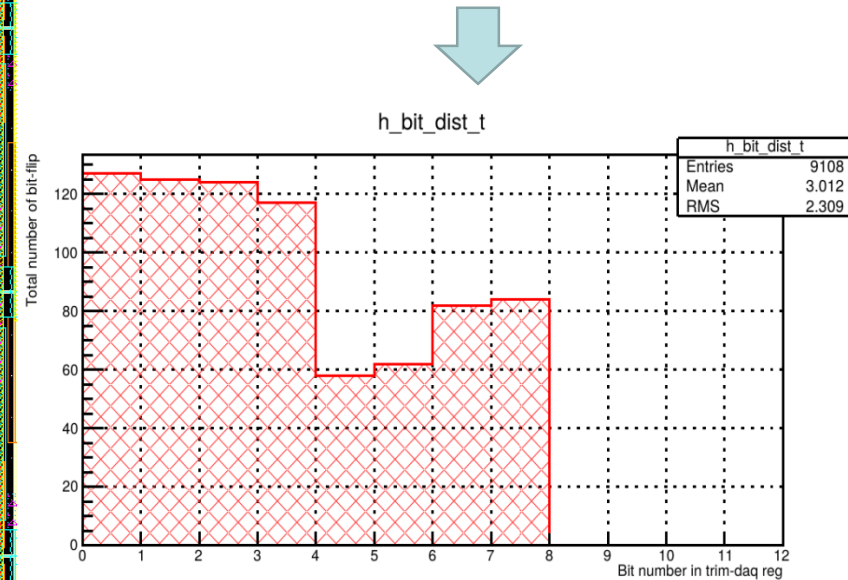
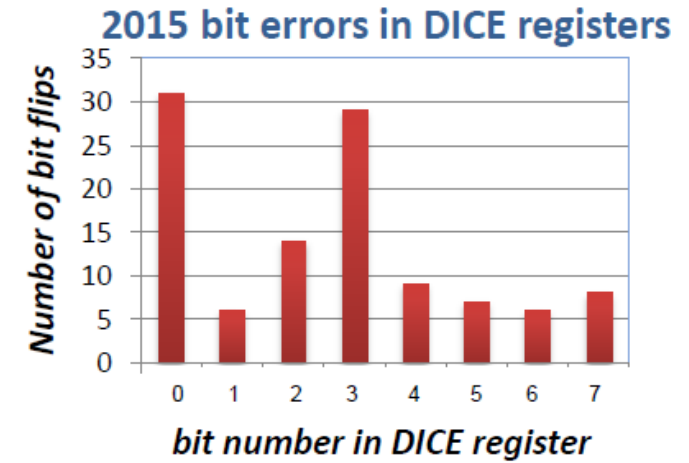
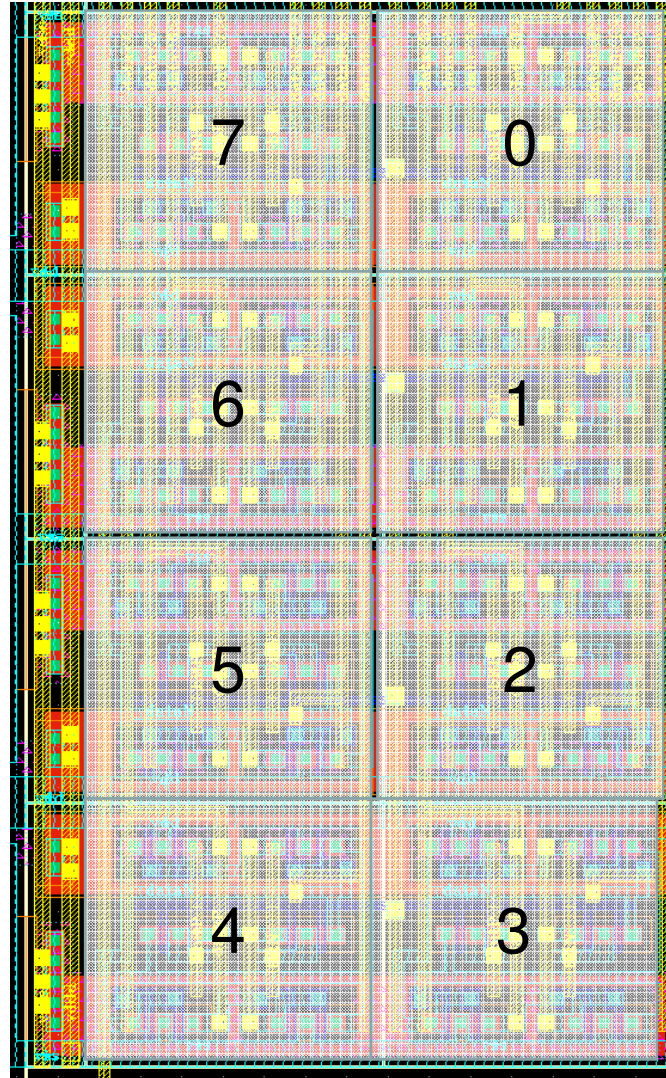
DICE Dual Interlocked Storage Cell

OLD



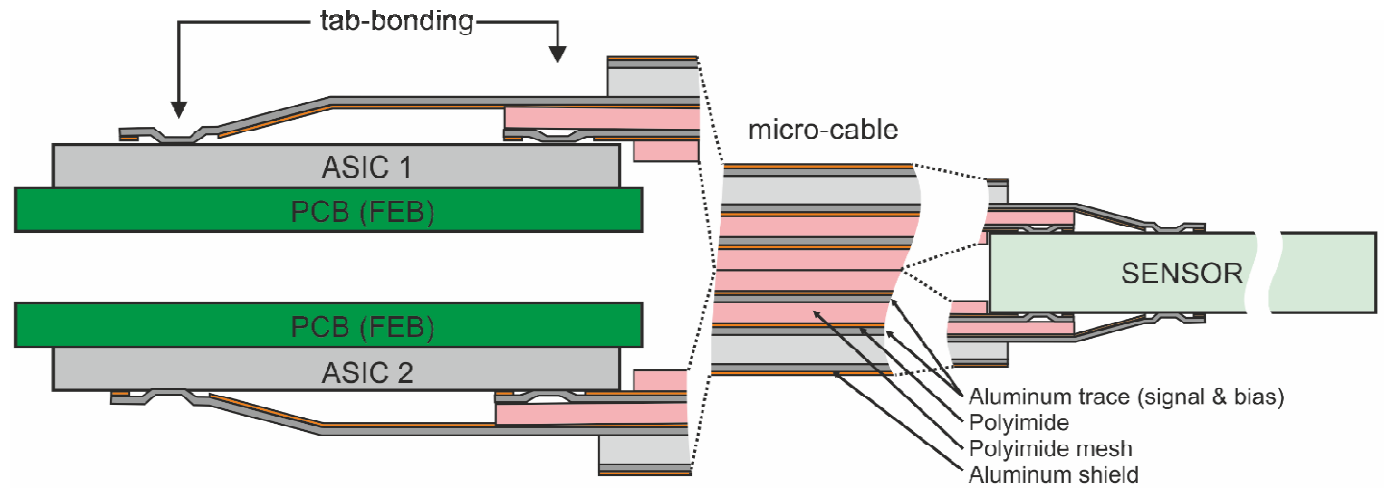
SEU immunity of the configuration memories

NEW (STS-XYTER2)

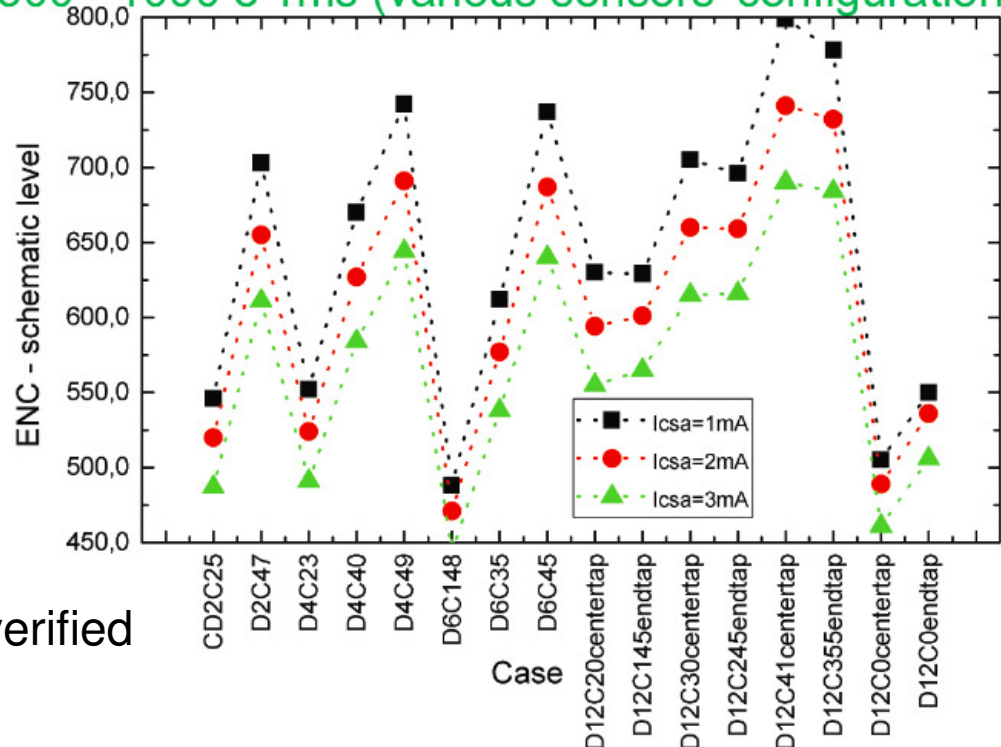


Thanks:
Joerg Lehnert
Adrian Rodriguez-Rodriguez

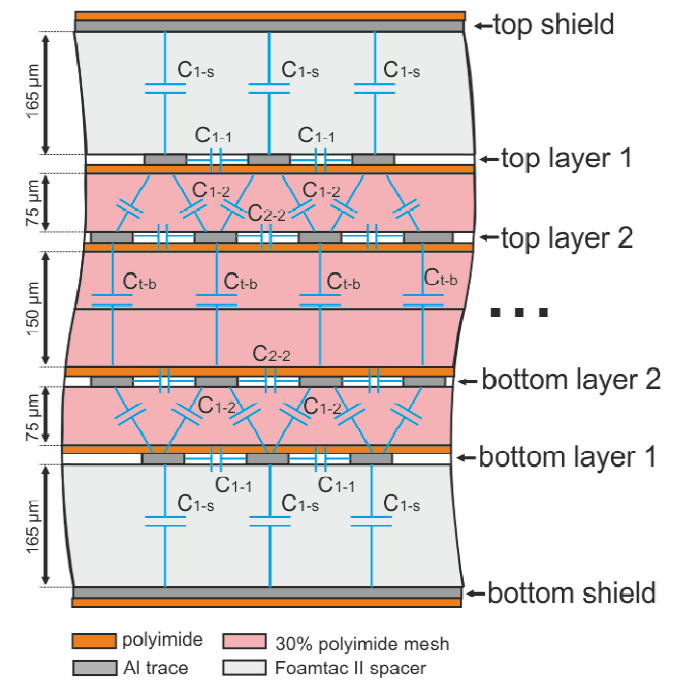




ENC < 500 - 1000 e⁻ rms (various sensors' configurations)



to be verified

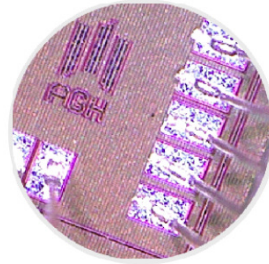


Summary

- STS/MUCH-XYTER2 ASIC was developed and fabricated
- Chip is an evolution of STS-XYTER full-size prototype with major improvements
 - Optimized for silicon microstrip-based STS detector sensor – microcable – ASIC – power co-design
 - Readout option for MUCH GEM sensors
- More, extensive tests are currently in progress
 - tests with GEMs @ VECC, India
 - characterization @ GSI, Darmstadt, Germany
 - beam test @ COSY, Juelich, Germany
- High-volume production planned 2017/2018



Thank you for your attention



Krzysztof KASINSKI,
Weronika ZUBRZYCKA,
Robert SZCZYGIEŁ

- K. Kasinski, R. Szczygiel, et al., JINST 2016 vol. 11
- K. Kasinski, R. Kleczek, R. Szczygiel, JINST 2016 vol. 11.
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- K. Kasinski, R. Kleczek, Proc. MIXDES (2016).
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- W. Zubrzycka, K. Kasinski, Proc. SPIE (2017).



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- AGH, Kraków:** P. Otfinowski, R. Kleczek
- GSI, Darmstadt:** J. Lehnert, A. Rodriguez, C. J. Schmidt, W. F. J. Mueller, P. Koczon, C. Simons et al.,
- WUT, Warsaw:** W. Zabolotny, G. Kasprowicz, A. Byszuk and others

<http://www.kmet.agh.edu.pl/katedra-metrologii/zespoly-badawcze/asics/?lang=en>

